Display Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 320240P TMH-PW-N

2,3“ TFT

Product Specification **Ver.: 1**

24.05.2016

Revision History

Revision	Date	Originator	Detail	Remarks
0	17.07.2015	MH	Initial Release	-
1	24.05.2016	MH	Modify Interface	P4

Table of Contents

1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size (Diagonal)	2.3”	-
LCD Type	TN TFT	-
Display Mode	Transmissive / Normally White	-
Resolution	320 x RGB x 240	Pixels
View Direction	6 O’clock	Best Image
Gray Scale Inversion Direction	12 O’clock	-
Module Outline	50.90 x 45.80 x 2.30 (max.) (Note1)	mm
Active Area	46.752 x 35.064	mm
Pixel Size	146.10 x 146.10	mm
Pixel Arrangement	R.G.B. Vertical-Stripe	-
Polarizer Surface Treatment	Normal	-
Display Colors	262k	-
Interface	6-Bit-RGB-Interface (Serial) + 3-Wire-SPI	-
Driver IC	ILI9342C (Ilitek)	-
With or Without Touch Panel	Without	-
Operating Temperature	-20°C to +70°C	ºC
Storage Temperature	-30°C to +80°C	ºC
Weight	~6	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

V_{SS}=0V, Ta=25ºC

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VCC	-0.3	3.6	V
Storage Temperature	T_{STG}	-30	80	ºC
Operating Temperature	T_{OP}	-20	70	ºC

Note 1: If Ta below 50ºC, the maximal humidity is 90%RH, if Ta over 50ºC, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item		Symbol	Min.	Typ.	Max.	Unit
Supply Voltage		VCC	3.0	3.2	3.3	V
Logic Low Input Voltage		V_{IL}	-0.3	-	0.2*VCC	V
Logic High Input Voltage		V_{IH}	0.8*VCC	-	VCC	V
Logic Low Output Voltage		V_{OL}	0	-	0.2VCC	V
Logic High Output Voltage		V_{OH}	0.8*VCC	-	VCC	V
Current Consumption All Black	Logic Analog	I_{CC+} I_{IN}	-	(6)	-	mA

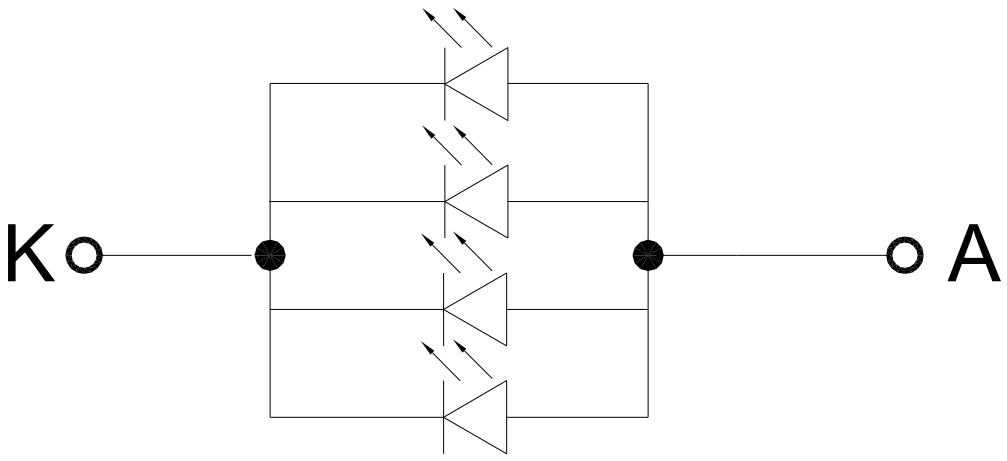
5. Backlight Characteristic

5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	Ta=25 ºC, I_F=20mA/LED	2.9	3.2	3.4	V
Forward Current	I_F	Ta=25 ºC, V_F=3.2V/LED	-	80	-	mA
Power Dissipation	P_D		-	256	-	mW
Uniformity	Avg		75	80	-	%
LED Lifetime (25°C)	-		-	30,000	-	Hrs
Drive Method	Constant Current					
LED Configuration	4 White LEDs in Parallel					

Note: LED life time defined as follows: The final brightness is at 50% of original brightness.
The environmental conducted under ambient air flow, at Ta=25±2°C, 60%RH±5%, I_F=20mA.

5.2. Backlighting Circuit



6. Optical Characteristics

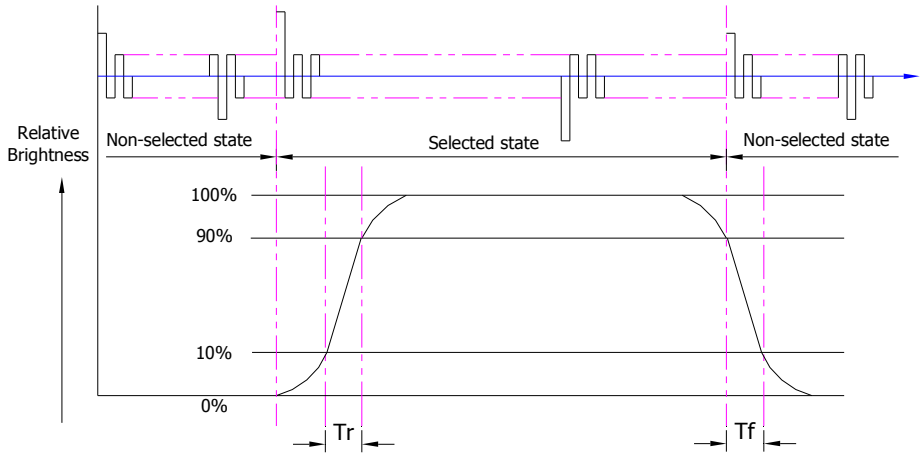
6.1. Optical Characteristics

Ta=25ºC, VCC=3.2V, TN LC+ Polarizer

	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
Backlight On (Transmissive Mode)	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle θx =φy =0º	240	300	-	cd/m²
	Contrast Ratio(See 6.3)		CR		400	500	-	
	Response Time (See 6.2)		TR+TF		-	20	30	ms
	Chromaticity Transmissive (See 6.5)	Red	XR		(0.508)	(0.558)	(0.608)	
			YR		(0.263)	(0.313)	(0.363)	
		Green	XG		(0.252)	(0.302)	(0.352)	
			YG		(0.578)	(0.628)	(0.678)	
		Blue	XB		(0.095)	(0.145)	(0.195)	
			YB		(0.051)	(0.101)	(0.151)	
		White	XW		(0.207)	(0.257)	(0.307)	
			YW		(0.269)	(0.319)	(0.369)	
	Viewing Angle (See 6.4)	Horizontal	θx+	Center CR≥10	60	70	-	Deg.
			θx-		60	70	-	
		Vertical	φy+		60	70	-	
			φy-		50	60	-	
	NTSC Ratio(Gamut)				-	45	50	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

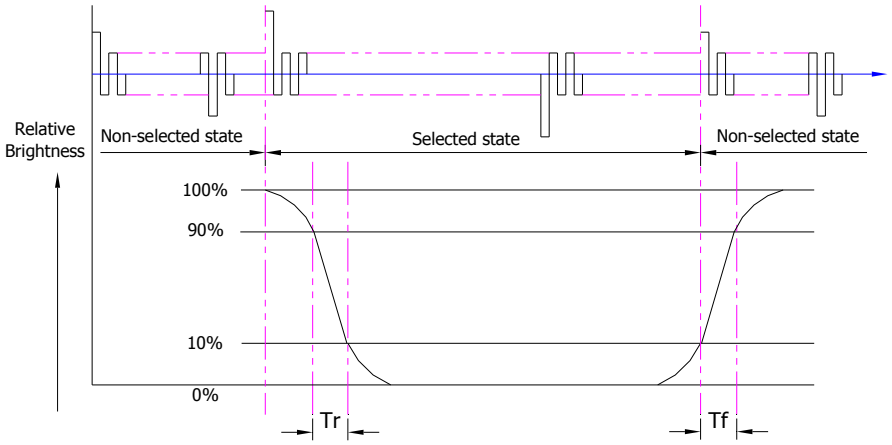


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note : Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note : Measuring machine: LCD-5100 or EQUI

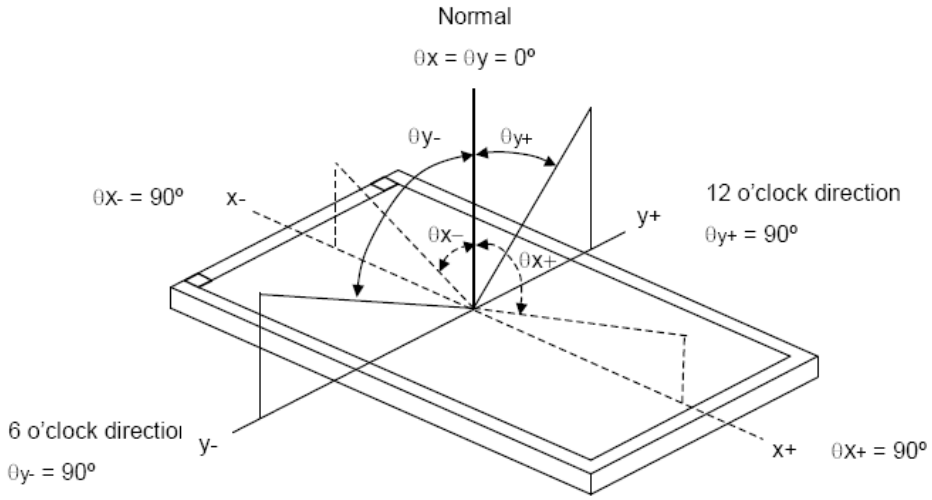
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



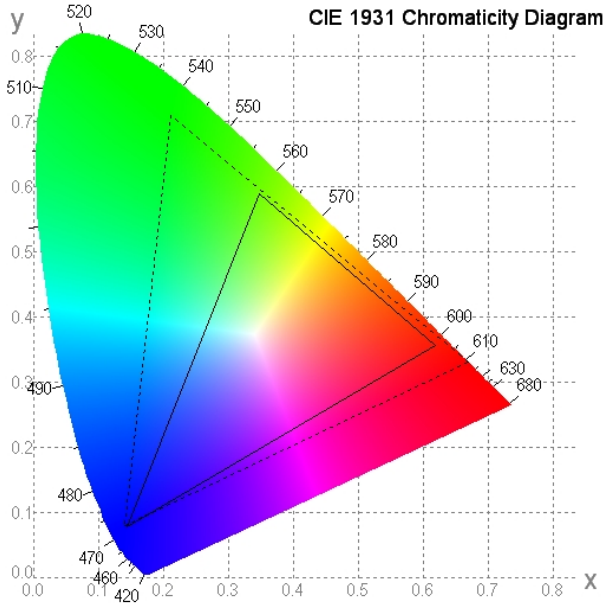
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

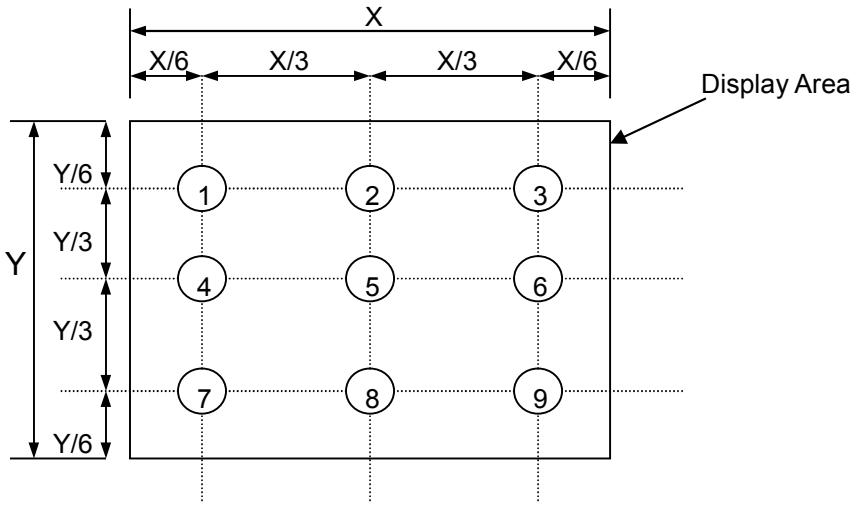
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: L_V = average (L_{P1}:L_{P9})

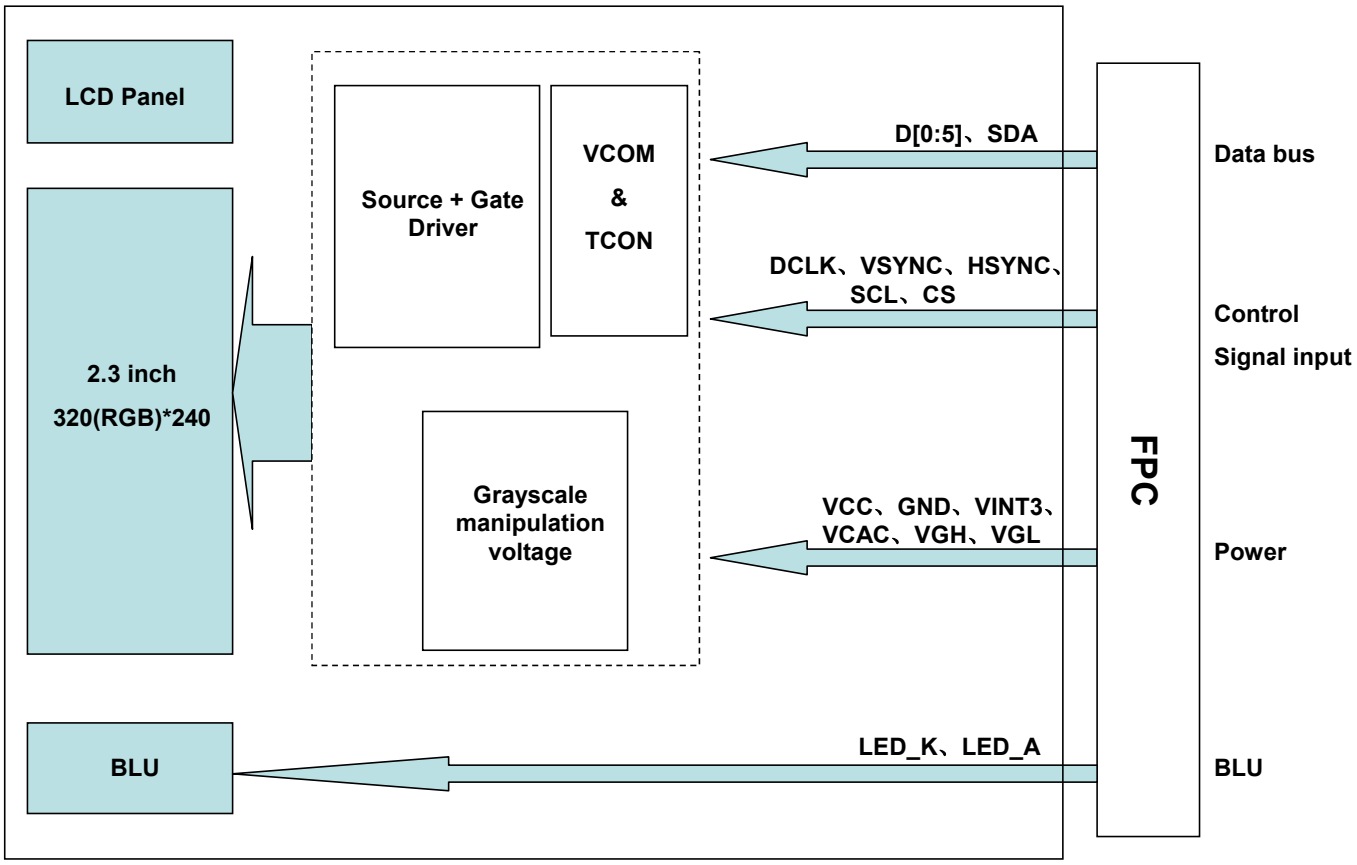
6.6.2. Uniformity = Minimal (L_{P1}:L_{P9}) / Maximal (L_{P1}:L_{P9}) * 100%

6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note : Measuring machine: BM-7



7. Block Diagram and Power Supply

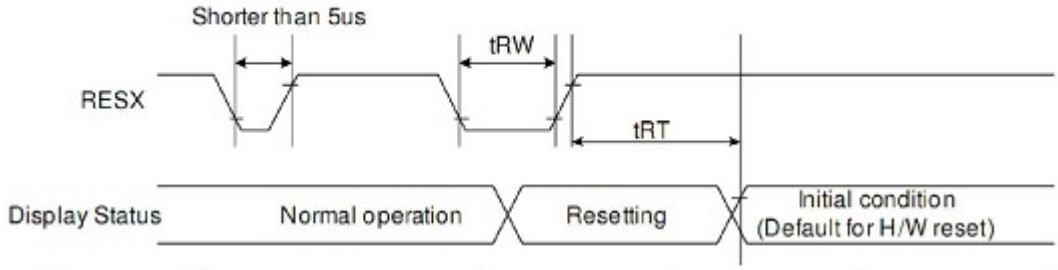


8. Interface Pins Definition

No.	Symbol	Function	Remark
1	NC	No connection.	
2	NC	No connection.	
3	D0	Data bus.	
4	D1	Data bus.	
5	D2	Data bus.	
6	D3	Data bus.	
7	D4	Data bus.	
8	D5	Data bus.	
9	DCLK	Pixel Clock Signal.	
10	VSYNC	Vertical Sync Signal.	
11	HSYNC	Horizontal Sync Signal.	
12	SCL	Serial Communication Clock Input.	
13	SDA	Serial Communication Data Input and Output.	
14	CS	Chip select signal.	
15	VCC	Supply voltage.	
16	GND	Ground.	
17	NC	No connection.	
18	LED_K	LED Cathode.	
19	GND	Ground.	
20	LED_A	LED Anode.	
21	NC	No connection.	
22	NC	No connection.	
23	NC	No connection.	
24	C1M	Connect the charge-pumping capacitor on C11P/C11N for generating DDVDH level.	
25	C1P		
26	NC	No connection.	
27	C2M	Connect the charge-pumping capacitor on C31P/C31N for generating DDVDH 3X level.	
28	C2P		
29	NC	No connection.	
30	C3M	Connect the charge-pumping capacitor on C21P/C21N for generating VGH, VGL level.	
31	C3P		
32	VINT3	Power supply for the source driver and VCOM driver.	
33	VCAC	A power supply pin for generating GVCL.	
34	NC	No connection.	
35	VGH	Supply for The Gate Driver.	
36	C4M	Connect the charge-pumping capacitor on C22P/C22N for generating DDVDL 3X level.	
37	C4P		
38	VGL	Supply for The Gate Driver.	
39	NC	No connection.	
40	NC	No connection.	

9. Timing Characteristics

9.1 Reset Timing



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

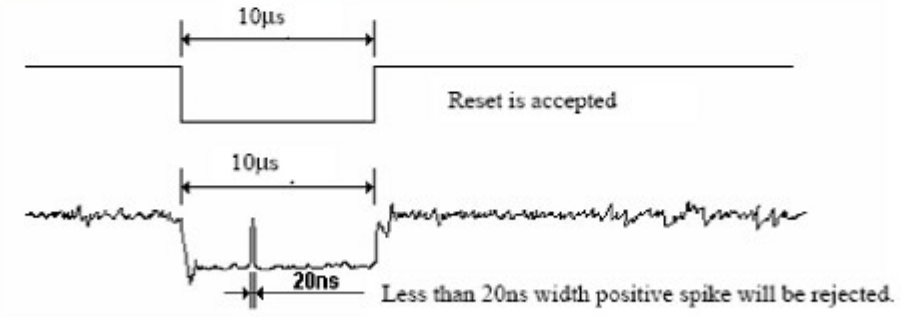
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:

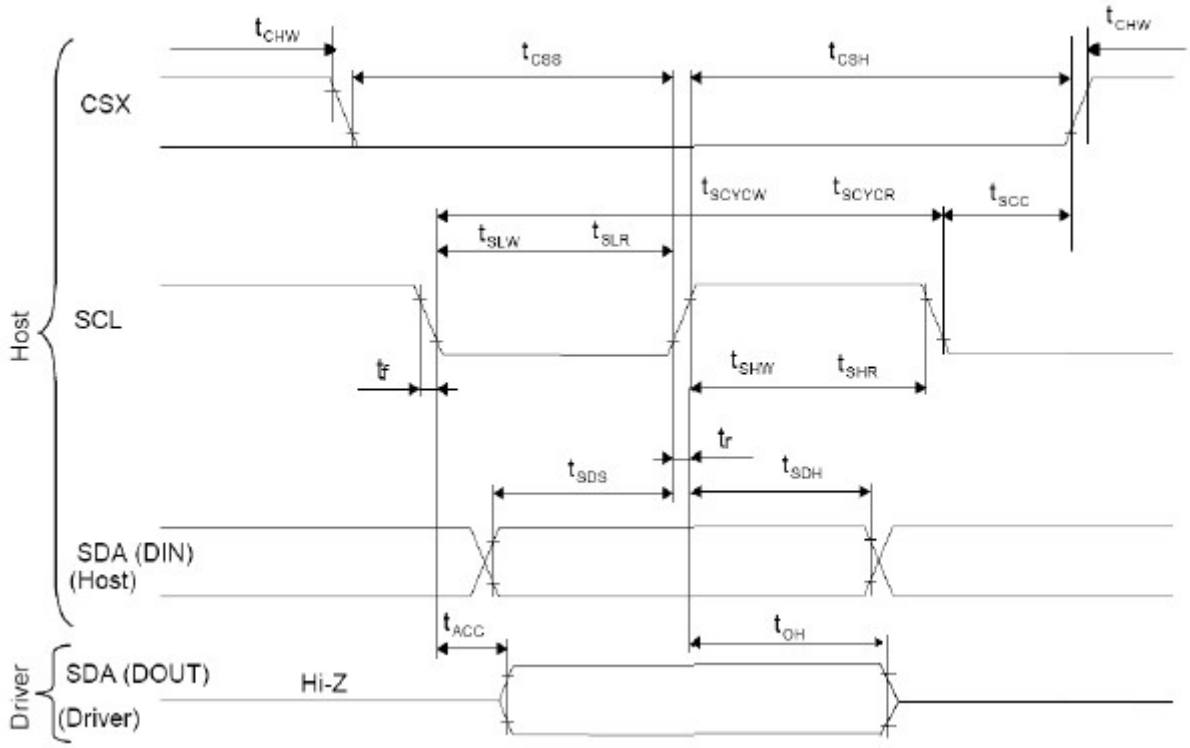


Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

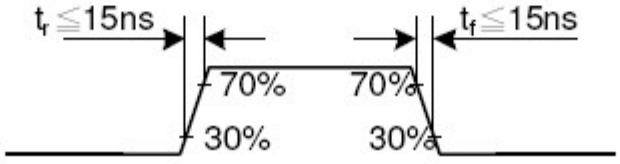
Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

9.2 Display Serial Interface Characteristics(3-line SPI system)

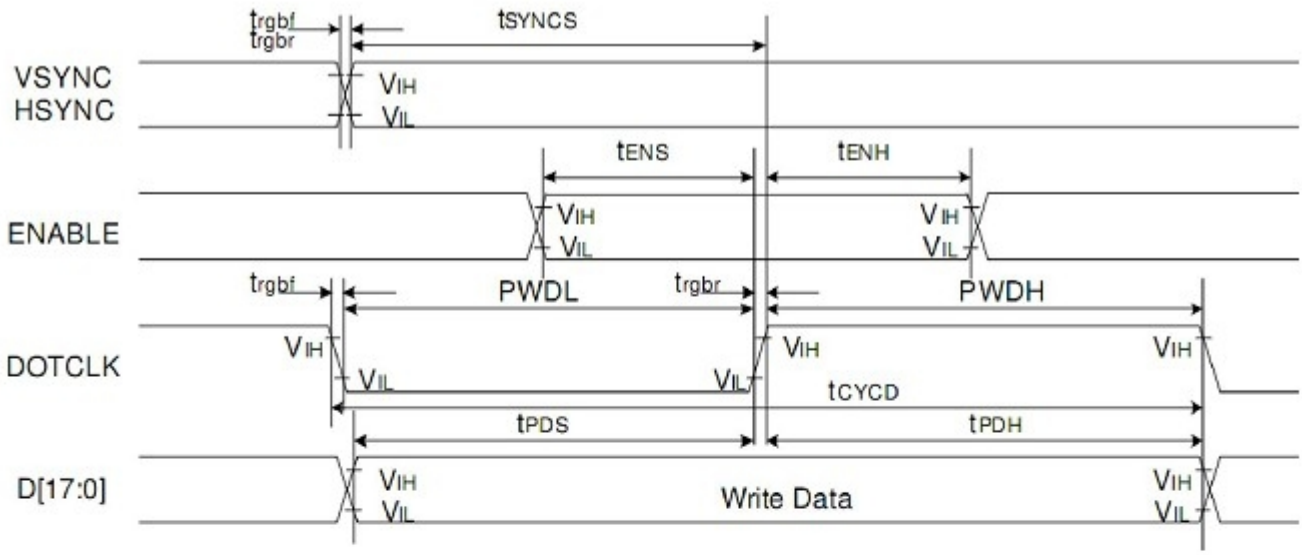


Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	35	-	ns	
	tslw	SCL "L" Pulse Width (Write)	35	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA (Input)	tsds	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	15	50	ns	
CSX	tscc	SCL-CSX	20	-	ns	
	tchw	CSX "H" Pulse Width	40	-	ns	
	tcss	CSX-SCL Time(write)	30	-	ns	
	tcsh		30	-	ns	

Note: Ta = 25 ℃, IOVCC=1.65V to 2.8V, VCI=2.6V to 3.3V, AGND=GND=0V



9.3 Parallel Interface Characteristics (6bit RGB Interface)



(VCI=3.0 to 3.3V, IOVCC=3.0 to 3.3V, Ta=25℃)

Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	33	-	ns	
	PWDL	DOTCLK low-level period	33	-	ns	
	t_{CYCD}	DOTCLK cycle time(18 bit)	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level pulse period	25	-	ns	
	PWDL	DOTCLK low-level pulse period	25	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

10. Quality Assurance

10.1 Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2 Standard for Quality Test

10.2.1 Sampling Plan:

GB2828.1-2012

Single sampling, normal inspection

10.2.2 Sampling Criteria:

Visual inspection: AQL 1.5%

Electrical functional: AQL 0.65%.

10.2.3 Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3 Nonconforming Analysis & Disposition

10.3.1 Nonconforming analysis:

10.3.1.1 Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2 After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3 If cannot finish the analysis on time, customer will be notified with the progress status.

10.3.2 Disposition of nonconforming:

10.3.2.1 Non-conforming product over PPM level will be replaced.

10.3.2.2 The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4 Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1 There is any discrepancy in standard of quality assurance.

10.4.2 Additional requirement to be added in product specification.

10.4.3 Any other special problem.

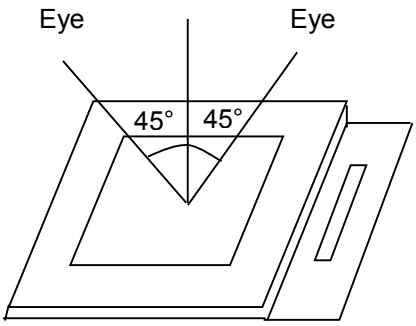
10.5 Standard of the Product Visual Inspection

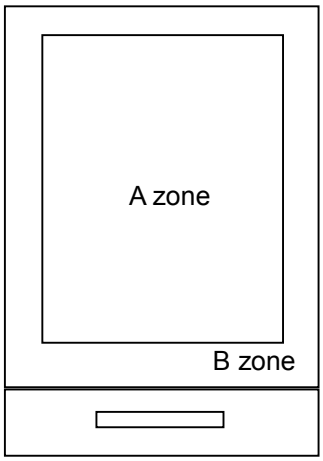
10.5.1 Appearance inspection:

10.5.1.1 The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

10.5.1.2 The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3 Definition of area: A Zone: Active Area, B Zone: Viewing Area,



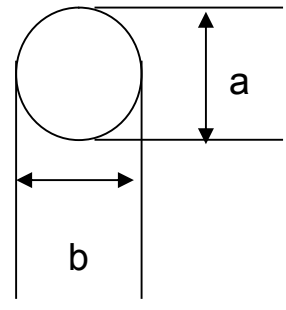


10.5.2 Basic principle:

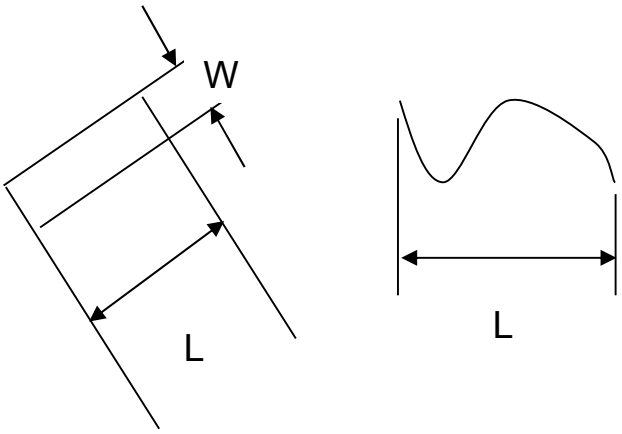
10.5.2.1 A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

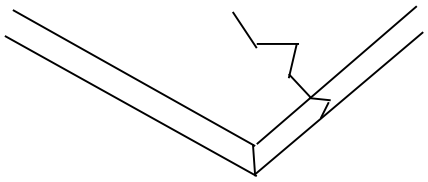
10.5.2.2 New item must be added on time when it is necessary.

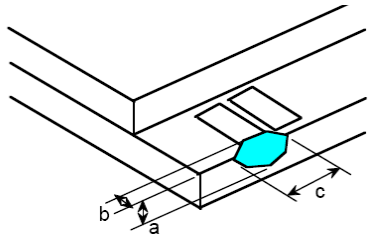
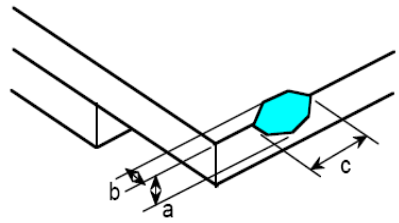
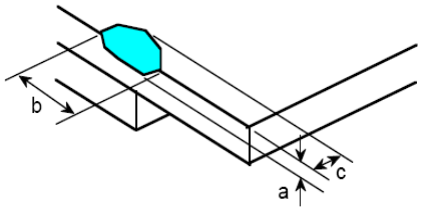
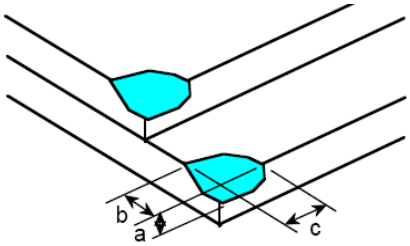
10.6 Inspection Specification

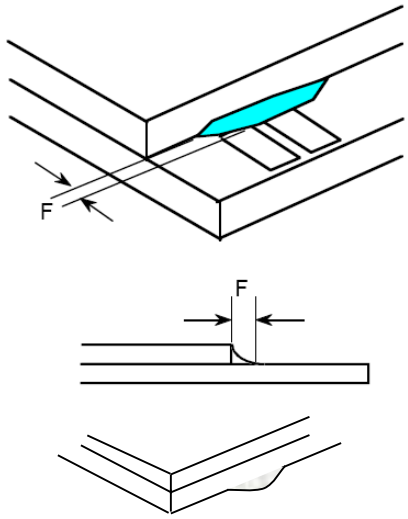
<table>
<tr><th>No.</th><th>Item</th><th>Criteria (Unit: mm)</th></tr>
<tr><td>01</td><td>Black / White spot
Foreign material
(Round type)
Pinholes
Stain
Particles inside cell.
(Minor defect)</td><td>


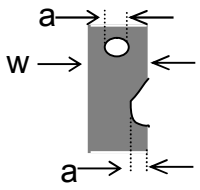
φ= (a + b) /2
<table>
<tr><th>Area / Size</th><th>Acc. Qty</th></tr>
<tr><td>φ≤0.10</td><td>Ignore</td></tr>
<tr><td>0.10<φ≤0.15</td><td>2</td></tr>
<tr><td>0.15<φ≤0.25</td><td>1</td></tr>
<tr><td>0.25<φ</td><td>0</td></tr>
<tr><td>Total</td><td>2 no include φ≤ 0.10</td></tr>
</table>
Distance between 2 defects should more than 3mm apart.
</td></tr>
</table>

<table>
<tr><td>02</td><td>Electrical Defect
(Minor defect)</td><td>
<table>
<tr><th></th><th>Display Area</th><th>Total</th><th rowspan="4">Note1</th></tr>
<tr><td>Bright dot</td><td>0</td><td>0</td></tr>
<tr><td>Dark dot</td><td>N≤2</td><td>N≤2</td></tr>
<tr><td>Total dot</td><td>N≤2</td><td>N≤2</td></tr>
<tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td><td>Note2</td></tr>
</table>
Remark:
1. Bright dot caused by scratch and foreign object accords to item 1.
</td></tr>
<tr><td>03</td><td>Black and White line
Scratch
Foreign material
(Line type)
(Minor defect)</td><td>


<table>
<tr><th>Length</th><th>Width</th><th>Acc. Qty</th></tr>
<tr><td>/</td><td>W ≦ 0.03</td><td>Ignore</td></tr>
<tr><td>L ≦ 2.5</td><td>0.03 ＜ W ≦ 0.05</td><td>3</td></tr>
<tr><td>L ≦ 2.5</td><td>0.05 ＜ W ≦ 0.10</td><td>2</td></tr>
<tr><td>/</td><td>0.1 ＜ W</td><td>0</td></tr>
<tr><td colspan="2">Total</td><td>3</td></tr>
</table>
Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.
</td></tr>
<tr><td>04</td><td>Glass Crack
(Minor defect)</td><td>

Crack is potential to enlarge, any type is not allowed.
</td></tr>
</table>

<table>
<tr><td>05</td><td>Glass Chipping Pad Area:
(Minor defect)
 
</td><td><table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>c > 3.0, b< 1.0</td><td>1</td></tr><tr><td>c< 3.0, b< 1.0</td><td>3</td></tr><tr><td colspan="2">a<Glass Thickness</td></tr></table></td></tr>
<tr><td>06</td><td>Glass Chipping Rear of Pad Area:
(Minor defect)
 
</td><td><table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>c > 3.0, b< 1.0</td><td>1</td></tr><tr><td>c< 3.0, b< 1.0</td><td>2</td></tr><tr><td>c< 3.0, b< 0.5</td><td>4</td></tr><tr><td colspan="2">a<Glass Thickness</td></tr></table></td></tr>
<tr><td>07</td><td>Glass Chipping Except Pad Area:
(Minor defect)
 
</td><td><table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>c > 3.0, b< 1.0</td><td>1</td></tr><tr><td>c< 3.0, b< 1.0</td><td>2</td></tr><tr><td>c< 3.0, b< 0.5</td><td>4</td></tr><tr><td colspan="2">a<Glass Thickness</td></tr></table></td></tr>
<tr><td>08</td><td>Glass Corner Chipping:
(Minor defect)
 
</td><td><table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>c < 3.0, b< 3.0</td><td>Ignore</td></tr><tr><td colspan="2">a<Glass Thickness</td></tr></table></td></tr>
</table>

<table>
<tr><td>09</td><td>Glass Burr:
(Minor defect)
 

</td><td><table><tr><th>Length</th><th>Acc. Qty</th></tr><tr><td>F < 1.0</td><td>Ignore</td></tr></table>
Glass burr don’t affect assemble and module dimension.</td></tr>
<tr><td>10</td><td>FPC Defect:
(Minor defect)
 
</td><td>10.1 Dent, pinhole width a<w/3.
(w: circuitry width.)
10.2 Open circuit is unacceptable.
10.3 No oxidation, contamination and distortion.</td></tr>
<tr><td>11</td><td>Bubble on Polarizer
(Minor defect)</td><td><table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>12</td><td>Dent on Polarizer
(Minor defect)</td><td><table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>13</td><td>Bezel</td><td>13.1 No rust, distortion on the Bezel.
13.2 No visible fingerprints, stains or other contamination.</td></tr>
</table>

14	Touch Panel	D: Diameter W: width L: length 14.1 Spot: D<0.25 is acceptable 0.25≤D≤0.4 2dots are acceptable and the distance between defects should more than 10 mm. D>0.4 is unacceptable 14.2 Dent: D>0.40 is unacceptable 14.3 Scratch: W≤0.03, L≤10 is acceptable, 0.03<W≤0.10, L≤10 is acceptable Distance between 2 defects should more than 10 mm. W>0.10 is unacceptable.
15	PCB	15.1 No distortion or contamination on PCB terminals. 15.2 All components on PCB must same as documented on the BOM/component layout. 15.3 Follow IPC-A-600F.
16	Soldering	Follow IPC-A-610C standard
17	Electrical Defect (Major defect)	The below defects must be rejected. 17.1 Missing vertical / horizontal segment, 17.2 Abnormal Display. 17.3 No function or no display. 17.4 Current exceeds product specifications. 17.5 LCD viewing angle defect. 17.6 No Backlight. 17.7 Dark Backlight. 17.8 Touch Panel no function.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7 Classification of Defects

10.7.1 Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

10.7.2 Two minor defects are equal to one major in lot sampling inspection.

10.8 Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

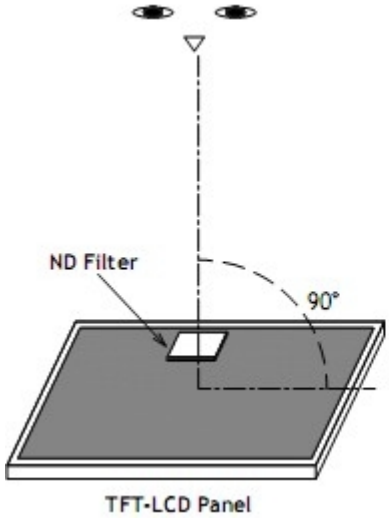
10.9 Packaging

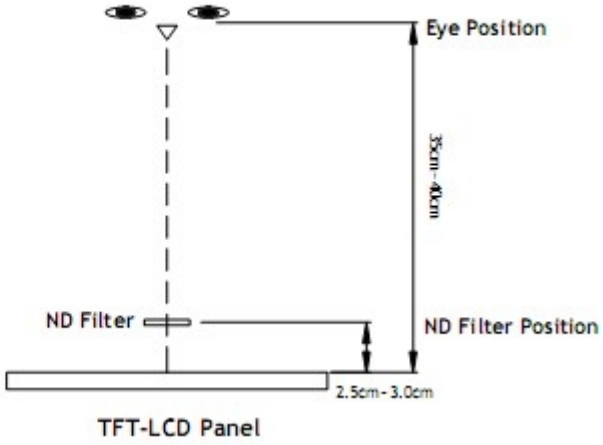
10.9.1 There should be no damage of the outside carton box, each packaging box should have one identical label.

10.9.2 Modules inside package box should have compliant mark.

10.9.3 All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.





Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	2	GB/T5170.14 -2009
8	Electrical Static Discharge	Air:±8KV 150pF/330Ω 5 times Contact:±4KV 150pF/330Ω 5 times	2	GB/T17626.2 -2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1 Safety

12.1.1 The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.

12.1.2 Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2 Handling

12.2.1 Reverse and use within ratings in order to keep performance and prevent damage.

12.2.2 Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3 Storage

12.3.1 Do not store the LCD module beyond the specified temperature ranges.

12.4 Metal Pin (Apply to Products with Metal Pins)

12.4.1 Pins of LCD and Backlight

12.4.1.1 Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2 Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

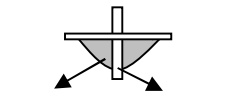
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

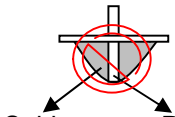
Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

12.4.1.3 Solder Wetting



Recommended



Not Recommended

12.4.2 Pins of EL

12.4.2.1 Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2 No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3 Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270～290℃

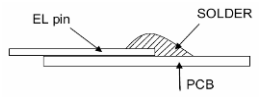
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

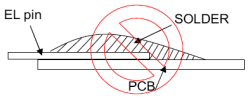
12.4.2.4 No horizontal press on the EL leads during soldering.

12.4.2.5 180° bend EL leads three times is not allowed.

12.4.2.6 Solder Wetting

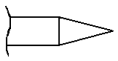


Recommended

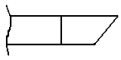


Not Recommended

12.4.2.7 The type of the solder iron:

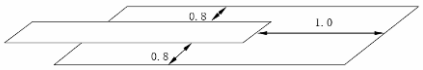


Recommended



Not Recommended

12.4.2.8 Solder Pad



12.5 Operation

12.5.1 Do not drive LCD with DC voltage

12.5.2 Response time will increase below lower temperature

12.5.3 Display may change color with different temperature

12.5.4 Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.

12.6 Static Electricity

12.6.1 CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.

12.6.2 The normal static prevention measures should be observed for work clothes and benches.

12.6.3 The module should be kept into anti-static bags or other containers resistant to static for storage.

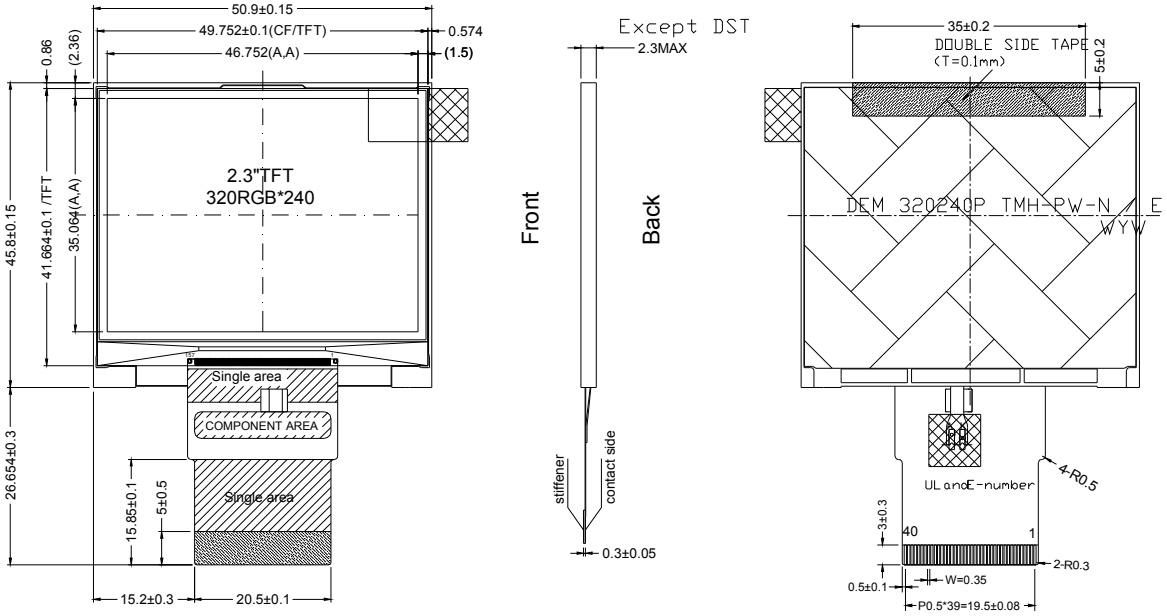
12.7 Limited Warranty

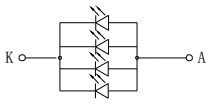
12.7.1 Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.

12.7.2 If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.

12.7.3 After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Outline Drawing





NOTES:
1.Display Type: 2.3"TFT
2.Viewing Direction: 6 O'CLOCK
3.Grayscale Inversion Direction: 12 O'CLOCK
4.Polarizer mode:Transmissive/Normal white / Anti-Glare
5.Operation Temperature: -20°C to +70°C
6.Storage Temperature: -30°C to +80°C
7.Driver/Controller IC: ILI9342C (Ilitek)
8.Logic Power Supply Voltage: 3.2 Volt (typ.)
9.Backlight: White, Lightguide (4LEDs, 80mA, 3.2Volt (typ.))
10.Brightness: 300cd/m2 (typ.)
11.LED Lifetime: 30.000h (typ.)

* Unspecification tolerance are ± 0.2mm

Pin assignment

PIN	SYMBOL
1	NC
2	NC
3	D0
4	D1
5	D2
6	D3
7	D4
8	D5
9	DCLK
10	VSYNC
11	HSYNC
12	SCL
13	SDA
14	CS
15	VCC
16	GND
17	NC
18	LED_K
19	GND
20	LED_A
21	NC
22	NC
23	NC
24	C1M
25	C1P
26	NC
27	C2M
28	C2P
29	NC
30	C3M
31	C3P
32	VINT3
33	VCAC
34	NC
35	VGH
36	C4M
37	C4P
38	VGL
39	NC
40	NC